# KBSW180161 Burn HEX File To Breakout Kit

We provide users reference code to modify based on development needs. we have breakout of 2 versions on the market: version 3.0 and 6.0, different versions have different reference code, please pay attention when burning hex files.

### How to check Breakout version

On border of the breakout you will see some marks, breakout 3.0 has a mark of "Ver 3.0" whereas breakout 6.0 has a mark of "R06"

#### Breakout 3.0

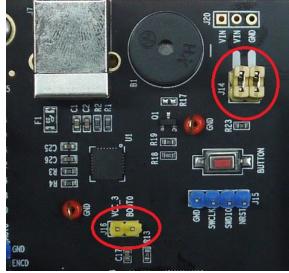
Breakout 3.0 layout please click here to download.

Reference code( breakout 3.0 compatible) please click *here* to download

Other tools: UART-USB board x 1DuPont line(both female)x 3USB cable x1  $\,$ 

#### Steps:

1. Find J16 and J14 on the breakout board, remove the jumpers on J14.



#### Breakout 6.0

Breakout 6.0 layout please click here to download.

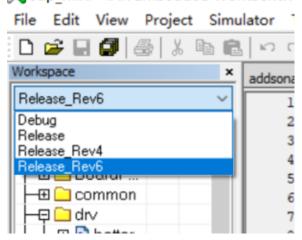
Reference code( breakout 6.0 compatible) please click *here* to download.

Other toolsUSB Type B cable x1

#### Remind

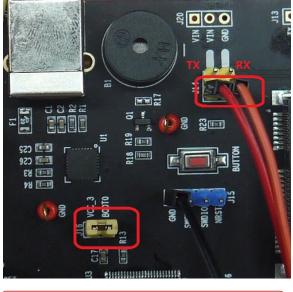
Please select workspace: **Release\_Rev6** in IAR7.6other project will be incompatible with breakout 6.0. the generated hex file will not be able to start the Slamware system.

## 💥 sdp mini - IAR Embedded Workbench



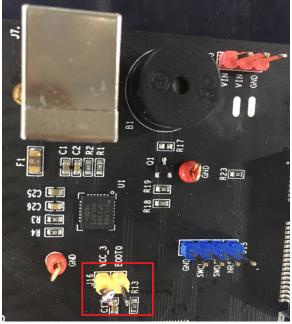
Steps:

2. Connect GND RX TX of the uart-usb board to J14 and any GND of breakout. Short J16 with a jumper

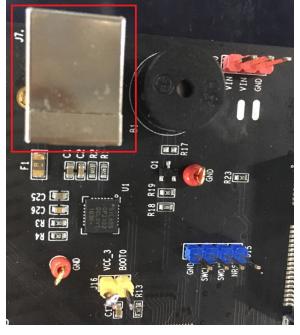


Please turn off the power supply during the above operation, otherwise you may damage the breakout.
It's necessary to short J16 during the hex loading.

1. Find J16 on the breakout, short J16 with a jumper.



2. connect J7 to you PC with the USB type B cable.



Please turn off the power supply during the above operation, otherwise you may damage the breakout.

It's necessary to short J16 during the hex loading.

3. Switch ON power supply, load the hex file with software like FlyMCU, set baud rate to 115200, if the file is successfully loaded, screen will show as follows:

统(X) 帮助(Y) Language 搜索串囗(V) Port:COM6 bps:1 机下载时的程序文件:	115200 www.mcuisp.com 编程器(W) 关于(Z)		
BH\3-Product\2-RSG\FW\slamwarekit_reference_code.20170711.hex	. //编程前重装文件		
持万用编程器   STMLSP   免费STMLAP   NXP ISP   EP968_RS232     开始编程(P)   一校验   一條控品和Isp   」注续涂录模式     读器件信息(R)   唐林芯片(Z)   读FLASH     建设字节区:   通程到FLASH时写选项字节等    读FLASH     设定选项字节等	DTR电平豐高(+3-+12V),度位 RTS豐高(+3-+12V),选择进入BootLoader 延时100毫秒 DTR电平变低(-312V)释放复位 RTS維持高 T好路線,4,接收到:79 1F 在串口COMG速楼成功的155000pps.耗时625毫秒 芯片内BootLoader版本号: 2.2 芯片PID: 00000414 STM32F10xxx_High-density 读出的选项字节: ASSAFEOFFOOFFOOFFOOFFOOFFOO 96位的芯片唯一序列号: [39FFD054042373720732343] [05DFF33 3734246 43237320] 芯片FIASI容量为512K3 芯片SRAM容量为65535KB(此信息仅供参考,新版本芯片已不包含此信息) 开始全片擦除(全片擦除时间会比较长,请耐心等候!) 全片擦除成功 DTR电平豐高(+3-+12V),這体进入BootLoader 延时100毫秒 DTR电平豐高(+3-+12V),這体进入BootLoader 延时100毫秒 DTR电平豐高(+3-+12V),這体进入BootLoader 延时100毫秒 DTR电平豐高(+3-+12V),這体过入BootLoader 延时100毫秒 DTR电平雙高(+312V),整改复位 RTS编持高 开始连接5,接收到:1F 1F 在串口COMG连接成功8115200bps,耗时922毫秒 芯片FDD: 00000414 STM32F10xxx_High-density 读出的选项字节: ASSAFF00FF00FF00FF00FF00FF00FF00 5位的芯片唯一序列号: [39FFD054642373720732343] [15DFFF39 3734248 43237320] 芯片FLASI容量为512K8 芯片FLASI容量为512K8 芯片FLASI容量为512K8	, 一切고	EŤ

4. Switch OFF the power supply, **remove the jumper of J16**, **reconnect jumpers of J14 if you are using breakout 3.0**. Switch ON power supply again and system will run the newly-burnt program.